



IFW
PATENT
8053-1015

IN THE U.S. PATENT AND TRADEMARK OFFICE

In re application of

Takekazu TANAKA

Conf. 1342

Application No. 10/602,044

Group 2814

Filed June 24, 2003

Examiner A. Chambliss

SEMICONDUCTOR PACKAGE, AND PRODUCTION
PROCESS FOR MANUFACTURING SUCH SEMICONDUCTOR
PACKAGE

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In compliance with Rules 1.97 and 1.98, and in fulfillment of the duty of disclosure under Rule 1.56, the accompanying document, a copy of which is attached to this statement, is made of record on the enclosed Form PTO-1449.

A concise explanation of the relevance of this item is that this reference was cited by the Japanese Patent Office in an Official Action. A copy of the Japanese Official Action in which it was cited is attached hereto, with what is believed to be the pertinent portion enclosed in a wavy line. **An English translation of the enclosed portion is also attached hereto.** JP 2000-114445 was previously cited in the Information Disclosure Statement filed March 21, 2005.

Under the provisions of 37 CFR 1.97(e), the undersigned hereby certifies that each item of information con-

tained in this Information Disclosure Statement was first cited in any communication from a foreign Patent Office in a counterpart foreign application not more than three months prior to the filing of this Statement.

Respectfully submitted,

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RJP/lk

September 28, 2005

EXAMINER: _____ **DATE CONSIDERED** _____

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

* Abstract provided for the Examiner's convenience